- 300-Mbps to 660-Mbps Serial LVDS Data Payload Bandwidth at 30-MHz to 66-MHz System Clock
- Pin-Compatible Superset of NSM DS92LV1023/DS92LV1224
- Chipset (Serializer/Deserializer) Power Consumption <450 mW (Typ) at 66 MHz</li>
- Synchronization Mode for Faster Lock

- Lock Indicator
- No External Components Required for PLL
- Low-Cost 28-Pin SSOP Package
- Industrial Temperature Qualified,
   T<sub>A</sub> = −40°C to 85°C
- Programmable Edge Trigger on Clock
- Flow-Through Pinout for Easy PCB Layout

#### SN65LV1023 Serializer

			_
SYNC1	1 0 2	28	DV <sub>CC</sub>
SYNC2	2 2	27	DV <sub>CC</sub>
D <sub>INO</sub> $\square$	3 2	26	□□ AV <sub>CC</sub>
$D_{IN1} \square \square$	4 2	25	AGND AGND
$D_{IN2} \square \square$	5 2	24	PWRDN
$D_{IN3} \square \square$	6 2	23	□□ AGND
	7 2	22	□ D <sub>O</sub> +
D <sub>IN5</sub> $\square$	8 2	21	□ D <sub>O</sub> -
$D_{IN6} \square \square$	9 2	20	AGND
$D_{IN7} \square \square$	10 1	9	DEN
$D_{IN8} \square$	11 1	8	AGND
	12 1	7	□□ AV <sub>CC</sub>
TCLK_R/F	13 1	6	DGND
TCLK $\Box$	14 1	5	DGND
L			

#### SN65LV1224 Deserializer

			1
AGND □	<b>┰</b> 1 ○	28	R <sub>OUT0</sub>
RCLK_R/F □	2	27	R <sub>OUT1</sub>
REFCLK	<b></b>	26	R <sub>OUT2</sub>
AV <sub>CC</sub> □	<b>□</b> 4	25	R <sub>OUT3</sub>
R <sub>I</sub> + □	<b>□</b> 5	24	$\square$ R <sub>OUT4</sub>
R <sub>I</sub> − □	<b>—</b> 6	23	DV <sub>CC</sub>
PWRDN 🗆	<b>□</b> 7	22	DGND
REN □	8	21	DV <sub>CC</sub>
RCLK □	<b></b> 9	20	DGND
LOCK [	10	19	R <sub>OUT5</sub>
AV <sub>CC</sub> □	<b>1</b> 1	18	R <sub>OUT6</sub>
AGND □	12	17	R <sub>OUT7</sub>
AGND □	13	16	R <sub>OUT8</sub>
DGND □	<b>II</b> 14	15	R <sub>OUT9</sub>
			J

## description

The SN65LV1023 serializer and SN65LV1224 deserializer comprise a 10-bit serdes chipset designed to transmit and receive serial data over LVDS differential backplanes at equivalent parallel word rates from 30 MHz to 66 MHz. Including overhead, this translates into a serial data rate between 360-Mbps and 792-Mbps payload encoded throughput.

Upon power up, the chipset link can be initialized via a synchronization mode with internally generated SYNC patterns, or the deserializer can be allowed to synchronize to random data. By using the synchronization mode, the deserializer establishes lock within specified, shorter time parameters.

The device can be entered into a power-down state when no data transfer is required. Alternatively, a mode is available to place the output pins in the high-impedance state without losing PLL lock.

The SN65LV1023 and SN65LV1224 are characterized for operation over ambient air temperature of  $-40^{\circ}$ C to  $85^{\circ}$ C.

#### ORDERING INFORMATION

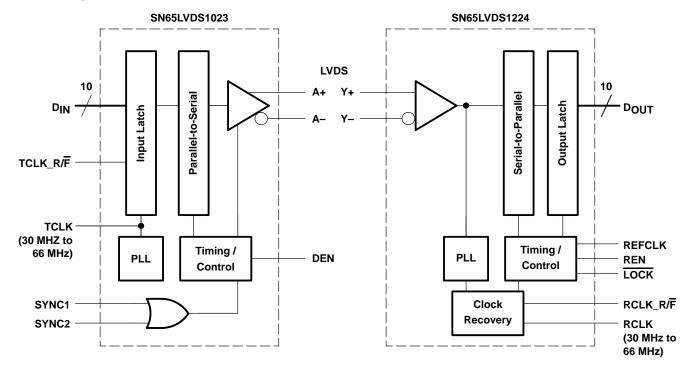
DEVICE	PART NUMBER
Serializer	SN65LV1023DB
Deserializer	SN65LV1224DB



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### block diagrams



#### functional description

The SN65LV1023 and SN65LV1224 are a 10-bit serializer/deserializer chipset designed to transmit data over differential backplanes or unshielded twisted pair (UTP) at clock speeds from 30 MHz to 66 MHz. The chipset has five states of operation: initialization mode, synchronization mode, data transmission mode, power-down mode, and high-impedance mode. The following sections describe each state of operation.

#### initialization mode

Initialization of both devices must occur before data transmission can commence. Initialization refers to synchronization of the serializer and deserializer PLLs to local clocks.

When  $V_{CC}$  is applied to the serializer and/or deserializer, the respective outputs enter the high-impedance state, while on-chip power-on circuitry disables internal circuitry. When  $V_{CC}$  reaches 2.45 V, the PLL in each device begins locking to a local clock. For the serializer, the local clock is the transmit clock (TCLK) provided by an external source. For the deserializer, a local clock must be applied to the REFCLK pin. The serializer outputs remain in the high-impedance state, while the PLL locks to the TCLK.



#### functional description (continued)

#### synchronization mode

The deserializer PLL must synchronize to the serializer in order to receive valid data. Synchronization can be accomplished in one of two ways:

Rapid Synchronization: The serializer has the capability to send specific SYNC patterns consisting of six
ones and six zeros switching at the input clock rate. The transmission of SYNC patterns enables the
deserializer to lock to the serializer signal within a deterministic time frame. This transmission of SYNC
patterns is selected via the SYNC1 and SYNC2 inputs on the serializer. Upon receiving valid SYNC1 or
SYNC2 pulse (wider than 6 clock cycles), 1026 cycles of SYNC pattern are sent.

When the deserializer detects edge transitions at the LVDS input, it attempts to lock to the embedded clock information. The deserializer  $\overline{\text{LOCK}}$  output remains high while its PLL locks to the incoming data or SYNC patterns present on the serial input. When the deserializer locks to the LVDS data, the  $\overline{\text{LOCK}}$  output goes low. When  $\overline{\text{LOCK}}$  is low, the deserializer outputs represent incoming LVDS data. One approach is to tie the deserializer  $\overline{\text{LOCK}}$  output directly to SYNC1 or SYNC2.

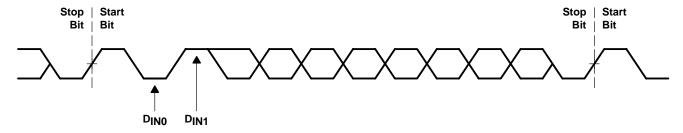
• Random-Lock Synchronization: The deserializer can attain lock to a data stream without requiring the serializer to send special SYNC patterns. This allows the SN65LV1224 to operate in open-loop applications. Equally important is the deserializer's ability to support hot insertion into a running backplane. In the open-loop or hot-insertion case, it is assumed the data stream is essentially random. Therefore, because lock time varies due to data stream characteristics, the exact lock time cannot be predicted. The primary constraint on the random lock time is the initial phase relation between the incoming data and the REFCLK when the deserializer powers up.

The data contained in the data stream can also affect lock time. If a specific pattern is repetitive, the deserializer could enter false lock—falsely recognizing the data pattern as the start/stop bits. This is referred to as repetitive multitransition (RMT); see Figure 1 for RMT examples. This occurs when more than one low-high transition takes place per clock cycle over multiple cycles. In the worst case, the deserializer could become locked to the data pattern rather than the clock. Circuitry within the deserializer can detect that the possibility of false lock exists. Upon detection, the circuitry prevents the LOCK output from becoming active until the potential false lock pattern changes. Notice that the RMT pattern only affects the deserializer lock time, and once the deserializer is in lock, the RMT pattern does not affect the deserializer state as long as the same data boundary happens each cycle. The deserializer does not go into lock unitil it finds a unique four consecutive cycles of data boundary (stop/start bits) at the same position.

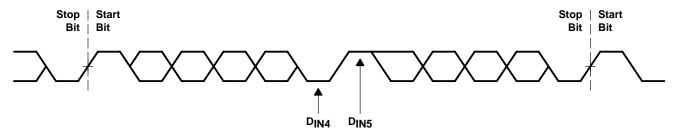
The deserializer stays in lock until it cannot detect the same data boundary (stop/start bits) for four consecutive cycles. Then the desiralizer goes out of lock and hunts for the new data boundary (stop/start bits). In the event of loss of synchronization, the  $\overline{LOCK}$  pin output goes high and the outputs (including RCLK) enter a high-impedance state. The user's system should monitor the  $\overline{LOCK}$  pin in order to detect a loss of synchronization. Upon detection of loss of lock, sending sync patterns for resynchronization is desirable if reestablishing lock within a specific time is critical. However, the deserializer can lock to random data as previously noted.

#### synchronization mode (continued)

DINO Held Low and DIN1 Held High



#### DIN4 Held Low and DIN5 Held High



#### DIN8 Held Low and DIN9 Held High

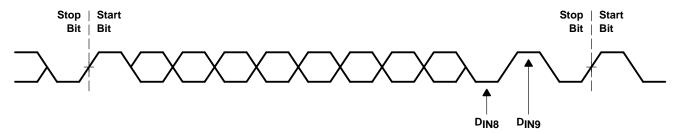


Figure 1. RMT Pattern Examples

#### data transmission mode

After initialization and synchronization, the serializer accepts parallel data from inputs  $D_{IN0}-D_{IN9}$ . The serializer uses the TCLK input to latch the incoming data. The TCLK\_R/ $\overline{F}$  pin selects which edge the serializer uses to strobe incoming data. If either of the SYNC inputs is high for 6 TCLK cycles, the data at  $D_{IN0}-D_{IN9}$  is ignored regardless of the clock edge selected and 1026 cycles of SYNC pattern are sent.

After determining which clock edge to use, a start and stop bit, appended internally, frames the data bits in the register. The start bit is always high and the stop bit is always low. The start and stop bits function as the embedded clock bits in the serial stream.

The serializer transmits serialized data and appended clock bits (10+2 bits) from the serial data output (DO $\pm$ ) at 12 times the TCLK frequency. For example, if TCLK is 66 MHz, the serial rate is  $66 \times 12 = 792$  Mbps. Because only 10 bits are input data, the useful data rate is 10 times the TCLK frequency. For instance, if TCLK = 66 MHz, the useful data rate is  $66 \times 10 = 660$  Mbps. The data source, which provides TCLK, must be in the range of 30 MHz to 66 MHz.



#### functional description (continued)

The serializer outputs (DO±) can drive point-to-point connections or limited multipoint or multidrop backplanes. The outputs transmit data when the enable pin (DEN) is high, PWRDN = high, and SYNC1 and SYNC2 are low. When DEN is driven low, the serializer output pins enter the high-impedance state.

Once the deserializer has synchronized to the serializer, the  $\overline{LOCK}$  pin transitions low. The deserializer locks to the embedded clock and uses it to recover the serialized data.  $R_{OUT}$  data is valid when  $\overline{LOCK}$  is low, otherwise  $R_{OUT0}-R_{OUT9}$  is invalid. The  $R_{OUT0}-R_{OUT9}$  data is strobed out by RCLK. The specific RCLK edge polarity to be used is selected by the RCLK\_R/F input. The  $R_{OUT0}-R_{OUT9}$ ,  $\overline{LOCK}$  and RCLK outputs can drive a maximum of three CMOS input gates (15-pF load. total for all three) with a 66-MHz clock.

#### power down

When no data transfer is required, the power-down mode can be used. The serializer and deserializer use the power-down state, a low-power sleep mode, to reduce power consumption. The deserializer enters power down when you drive PWRDN and REN low. The serializer enters power down when you drive PWRDN low. In power down, the PLL stops and the outputs enter a high-impedance state, which disables load current and reduces supply current to the milliampere range. To exit power down, you must drive the PWRDN pin high.

Before valid data exchanges between the serializer and deserializer can resume, you must reinitialize and resynchronize the devices to each other. Initialization of the serializer takes 1026 TCLK cycles. The deserializer initialize and drives LOCK high until lock to the LVDS clock occurs.

#### high-impedance mode

The serializer enters the high-impedance mode when the DEN pin is driven low. This puts both driver output pins (DO+ and DO-) into a high-impedance state. When you drive DEN high, the serializer returns to the previous state, as long as all other control pins remain static (SYNC1, SYNC2, PWRDN, TCLK\_R/F). When the REN pin is driven low, the deserializer enters high-impedance mode. Consequently, the receiver output pins (R<sub>OUT0</sub>-R<sub>OUT9</sub>) and RCLK are placed into the high-impedance state. The LOCK output remains active, reflecting the state of the PLL.

#### **Deserializer Truth Table**

INPUT	s	OUTPUTS			
PWRDN	REN	ROUT[0:9]	RCLK		
Н	Н	Z	Н	Z	
Н	Н	Active	L	Active	
L	Х	Z	Z	Z	
Н	L	Z	Active	Z	

- NOTES: 1. LOCK output reflects the state of the deserializer with regard to the selected data stream.
  - RCLK active indicates the RCLK is running if the deserializer is locked. The timing of RCLK with respect to ROUT is determined by RCLK\_R/F.
  - 3. ROUT and RCLK are 3-stated when LOCK is asserted high.



#### **Terminal Functions**

## serializer

PIN	NAME	DESCRIPTION
18, 20, 23, 25	AGND	Analog circuit ground (PLL and analog circuits)
17, 26	AVCC	Analog circuit power supply (PLL and analog circuits)
19	DEN	LVTTL logic input. Low puts the LVDS serial output into the high-impedance state. High enables serial data output.
15, 16	DGND	Digital circuit ground
3-12	D <sub>IN0</sub> – D <sub>IN9</sub>	Parallel LVTTL data inputs
21	D <sub>O</sub> -	Inverting LVDS differential output
22	D <sub>O</sub> +	Noninverting LVDS differential output
27, 28	DV <sub>CC</sub>	Digital circuit power supply
24	PWRDN	LVTTL logic input. Asserting this pin low turns off the PLL and places the outputs into the high-impedance state, putting the device into a low-power mode.
1, 2	SYNC1, SYNC2	LVTTL logic inputs SYNC1 and SYNC2 are ORed together. When at least one of the two pins is asserted high for 6 cycles of TCLK, the serializer initiates transmission of a minimum 1026 SYNC patterns. If after completion of the transmission of 1026 patterns SYNC continues to be asserted, then the transmission continues until SYNC is driven low and if the time SYNC holds > 6 cycles, another 1026 SYNC pattern transmission initiates.
13	TCLK_R/F	LVTTL logic input. Low selects a TCLK falling-edge data strobe; high selects a TCLK rising-edge data strobe.
14	TCLK	LVTTL-level reference clock input. The SN65LV1023 accepts a 30-MHz to 66-MHz clock. TCLK strobes parallel data into the input latch and provides a reference frequency to the PLL.

## deserializer

PIN	NAME	DESCRIPTION
1, 12, 13	AGND	Analog circuit ground (PLL and analog circuits)
4, 11	AVCC	Analog circuit power supply (PLL and analog circuits)
14, 20, 22	DGND	Digital circuit ground
21, 23	DV <sub>CC</sub>	Digital circuit power supply
10	LOCK	LVTTL level output. LOCK goes low when the deserializer PLL locks onto the embedded clock edge.
7	PWRDN	LVTTL logic input. Asserting this pin low turns off the PLL and places outputs into a high-impedance state, putting the device into a low-power mode.
2	RCLK_R/F	LVTTL logic input. Low selects an RCLK falling-edge data strobe; high selects an RCLK rising-edge data strobe.
9	RCLK	LVTTL level output recovered clock. Use RCLK to strobe R <sub>OUTx</sub> .
3	REFCLK	LVTTL logic input. Use this pin to supply a REFCLK signal for the internal PLL frequency.
8	REN	LVTTL logic input. Low places ROUT0-ROUT9 and RCLK in the high-impedance state.
5	R <sub>I</sub> +	Serial data input. Noninverting LVDS differential input
6	R <sub>I</sub> –	Serial data input. Inverting LVDS differential input
15-19, 24-28	ROUT0-ROUT9	Parallel LVTTL data outputs



## SN65LV1023/SN65LV1224 30-MHz TO 66-MHz, 10:1 LVDS SERIALIZER/DESERIALIZER

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## absolute maximum ratings (unless otherwise noted)†

V <sub>CC</sub> to GND	0.3 V to 4 V
LVTTL input voltage	$-0.3 \text{ V to } (V_{CC} + 0.3 \text{ V})$
LVTTL output voltage	$-0.3 \text{ V to } (V_{CC} + 0.3 \text{ V})$
LVDS receiver input voltage	0.3 V to 3.9 V
LVDS driver output voltage	0.3 V to 3.9 V
LVDS output short circuit duration	10 ms
Electrostatic discharge: HBM	up to 6 kV
MM	up to 200 V
Junction temperature	150°C
Storage temperature	– 65°C to 150°C
Lead temperature (soldering, 4 seconds)	260°C
Maximum package power dissipation, T <sub>A</sub> = 25°C	1.27 W
Package derating	10.3 mW/°C above 25°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub> <sup>‡</sup>	3	3.3	3.6	V
Receiver input voltage range	0		2.4	V
Receiver input common mode range, V <sub>CM</sub>	$\frac{V_{ID}}{2}$		$2.4 - \left(\frac{V_{ID}}{2}\right)$	V
Supply noise voltage			100	mV <sub>P</sub> _P
Operating free-air temperature, T <sub>A</sub>	-40	25	85	°C

<sup>‡</sup> By design, DVCC and AVCC are separated internally and does not matter what the difference is for | DVCC–AVCC |, as long as both are within 3 V to 3.6 V.



## electrical characteristics over recommended operating supply and temperature ranges (unless otherwise noted)

	PARAMETER	TEST CONDITION	IS	MIN	TYP	MAX	UNIT
SERIAL	IZER LVCMOS/LVTTL DC SPECIFICATIONS	(see Note 4)					
VIH	High-level input voltage			2		Vcc	V
VIL	Low-level input voltage			GND		0.8	V
VCL	Input clamp voltage	I <sub>CL</sub> = -18 mA			-0.86	-1.5	V
I <sub>IN</sub>	Input current (see Note 5)	V <sub>IN</sub> = 0 V or 3.6 V		-200	±100	200	μΑ
DESERI	IALIZER LVCMOS/LVTTL DC SPECIFICATIO	NS (see Note 6)					
VIH	High-level input voltage			2		Vcc	V
VIL	Low-level input voltage			GND		0.8	V
VCL	Input clamp voltage	I <sub>CL</sub> = -18 mA			-0.62	-1.5	V
I <sub>IN</sub>	Input current (pull-up and pull-down resistors on inputs)	V <sub>IN</sub> = 0 V or 3.6 V		-200		200	μΑ
Vон	High-level output voltage	I <sub>OH</sub> = -5 mA		2.2	3	Vcc	V
VOL	Low-level output voltage	I <sub>OL</sub> = 5 mA		GND	0.25	0.5	V
los	Output short-circuit current	V <sub>OUT</sub> = 0 V		-15	-47	-85	mA
loz	High-impedance output current	PWRDN or REN = 0.8 V, V <sub>OUT</sub> = 0 V or V <sub>CC</sub>		-10	±1	10	μΑ
SERIAL	IZER LVDS DC SPECIFICATIONS (apply to p	pins DO+ and DO-)					
VOD	Output differential voltage (DO+)–(DO–)	$R_L$ = 27 Ω, See Figure 18		350	450		mV
ΔV <sub>OD</sub>	Output differential voltage unbalance					35	mV
Vos	Offset voltage			1.1	1.2	1.3	V
ΔVos	Offset voltage unbalance				4.8	35	mV
los	Output short circuit current	D0 = 0 V, D <sub>INx</sub> = high, PWRDN and DEN = 2.4 V			-10	-90	mA
loz	High-impedance output current	PWRDN or DEN = 0.8 V, DO = 0	V or V <sub>CC</sub>	-10	±1	10	μΑ
I <sub>OX</sub>	Power-off output current	V <sub>CC</sub> = 0 V, DO = 0 V or 3.6 V		-20	±1	25	μΑ
DESERI	IALIZER LVDS DC SPECIFICATIONS (apply	to pins RI+ and RI–)					
VTH	Differential threshold high voltage	V <sub>CM</sub> = 1.1 V				50	mV
VTL	Differential threshold low voltage			-50			mV
1	lanut aurrant	V <sub>IN</sub> = 2.4 V, V <sub>CC</sub> = 3.6 V or 0 V		-10	±1	15	
l'IN	Input current	V <sub>IN</sub> = 0 V, V <sub>CC</sub> = 3.6 V or 0 V		-10	±0.05	10	μΑ
SERIAL	IZER SUPPLY CURRENT (applies to pins D	VCC and AVCC)					
1	Coriolizor aupply aurrent worst ages	D 27 O. Soo Figure 2	f = 30 MHz		30	45	mA
ICCD	Serializer supply current worst case	$R_L = 27 \Omega$ , See Figure 2	f = 66 MHz		55	70	ША
ICCXD	Serializer supply current	PWRDN = 0.8 V			200	500	μΑ
DESERI	IALIZER SUPPLY CURRENT (applies to pins	DVCC and AVCC)					
laan	Descriptives supply surrent worst sees	C <sub>L</sub> = 15 pF, See Figure 3	f = 30 MHz		40	50	mA
ICCR	Deserializer supply current, worst case	C <sub>L</sub> = 15 μr, see rigule 3	f = 66 MHz		80	95	IIIA
ICCXR	Deserializer supply current, power down	PWRDN = 0.8 V, REN = 0.8 V			0.36	1	mA

NOTES: 4. Apply to D<sub>IN0</sub>-D<sub>IN9</sub>, TCLK, PWRDN, TCLK\_R/F, SYNC1, SYNC2, DEN
5. High I<sub>IN</sub> values are due to pull-up and pull-down resistors on the inputs.
6. Apply to pins PWRDN, RCLK\_R/F, REN, REFCLK = inputs; apply to pins R<sub>OUTx</sub>, RCLK, LOCK = outputs



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# serializer timing requirements for TCLK over recommended operating supply and temperature ranges (unless otherwise specified)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> TCP	Transmit clock period		15.15	Т	33.33	ns
<sup>t</sup> TCIH	Transmit clock high time		0.4T	0.5T	0.6T	ns
<sup>t</sup> TCIL	Transmit clock low time		0.4T	0.5T	0.6T	ns
t <sub>t</sub> (CLK)	TCLK input transition time			3	6	ns
<sup>t</sup> JIT	TCLK input jitter	See Figure 17			150	ps (RMS)

## serializer switching characteristics over recommended operating supply and temperature ranges (unless otherwise specified)

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
tTLH(L)	LVDS low-to-high transition time		$R_L = 27 \Omega$ , $C_L = 10 pF to GND$ ,		0.2	0.4	ns
tLTHL(L)	LVDS high-to-low transition time		See Figure 4		0.25	0.4	ns
t <sub>su(DI)</sub>	D <sub>IN0</sub> -D <sub>IN9</sub> setup to TCLK		$R_L = 27 \Omega$ , $C_L = 10 pF to GND$ ,	0.5			ns
t <sub>su(DI)</sub>	D <sub>IN0</sub> -D <sub>IN9</sub> hold from TCLK		See Figure 7	4			ns
<sup>t</sup> d(HZ)	DO± high-to-high-impedance-sta	ate delay			2.5	5	
t <sub>d</sub> (LZ)	DO± low-to-high-impedance-state	te delay			2.5	5	
<sup>t</sup> d(ZH)	DO± high-to-high-impedance-sta	ite-to-	$R_L$ = 27 Ω, $C_L$ = 10 pF to GND, See Figure 8		5	10	ns
<sup>t</sup> d(ZL)	DO± high-to-high-impedance-stadelay	ate-to-low			6.5	10	
tw(SPW)	SYNC pulse duration		D. 27 O See Figure 40	6×tTCP			ns
t(PLD)	Serializer PLL lock time		$R_L$ = 27 Ω, See Figure 10	1026×tTCP			ns
<sup>t</sup> d(S)	Serializer delay		$R_L$ = 27 Ω, See Figure 11		t <sub>T</sub>	<u>CP</u> + 3.6	ns
	Determinate the title in	30 MHz	D 07.0.0 40 Etc. OND			230	
<sup>t</sup> DJIT	Deterministic jitter	66 MHz	$R_L = 27 \Omega$ , $C_L = 10 pF$ to GND		150	ps	
<sup>t</sup> RJIT	Random jitter	-	$R_L = 2.7 \Omega$ , $C_L = 10 pF to GND$		10	19	ps (RMS)

## SN65LV1023/SN65LV1224 30-MHz TO 66-MHz, 10:1 LVDS SERIALIZER/DESERIALIZER

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## deserializer timing requirements for REFCLK over recommended operating supply and temperature ranges (unless otherwise specified)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> RFCP	REFCLK period		15.15	T	33.33	ns
<sup>t</sup> RFDC	REFCLK duty cycle		30%	50%	70%	
t <sub>t</sub> (RF)	REFCLK transition time			3	6	ns

## deserializer switching characteristics over recommended operating supply and temperature ranges (unless otherwise specified)

	PARAMETER	TEST CONDITIONS	PIN/FREQ	MIN	TYP	MAX	UNIT	
t(RCP)	Receiver out clock period	t(RCP) = t(TCP), See Figure 11	RCLK	15.15		33.33	ns	
tTLH(C)	CMOS/TTL low-to-high transition time	C <sub>L</sub> = 15 pF,	ROUT0-ROUT9, LOCK, RCLK		1.2	2.5	- ns	
tTHL(C)	CMOS/TTL high-to-low transition time	See Figure 5			1.1	2.5		
t <sub>d</sub> (D)	Deserializer delay, See Figure 12	Room temperature, 3.3 V	30 MHz	2×t <sub>RCP</sub> + 7 2.8		2.833×t <sub>RCP</sub> + 11		
			66 MHz	2×t <sub>RCP</sub> + 4		2.833×t <sub>RCP</sub> + 7	ns	
4	R <sub>OUTx</sub> data valid before RCLK	See Figure 13	RCLK 30 MHz	0.4×tRCP	0.5×t <sub>RCP</sub>		ns	
t(ROS)			RCLK 66 MHz	0.4×tRCP	0.5×t <sub>RCP</sub>			
<b>4</b>	R <sub>OUTx</sub> data valid after RCLK		30 MHz	−0.4×tRCP	−0.5×t <sub>RCP</sub>			
t(ROH)			66 MHz	−0.4×t <sub>RCP</sub>	−0.5×t <sub>RCP</sub>			
t(RDC)	RCLK duty cycle			40%	50%	60%		
<sup>t</sup> d(HZ)	High-to-high-impedance state delay	See Figure 14	R <sub>OUT0</sub> -R <sub>OUT9</sub>		6.5	8	ns	
t <sub>d(LZ)</sub>	Low-to-high-impedance state delay				4.7	8	ns	
<sup>t</sup> d(HR)	High-impedance state- to-high delay				5.3	8	ns	
<sup>t</sup> d(ZL)	High-impedance-state-to -low delay				4.7	8	ns	
t(DSR1)	Deserializer PLL lock time from PWRDN (with SYNCPAT)	See Figure 15, Figure 16, and Note 7	30 MHz			(1024+26)tRFCP		
			66 MHz	(1024+26)t <sub>RFCP</sub>			μs	
<b>+</b>	Deserializer PLL lock time from SYNCPAT		30 MHz			0.3	]	
<sup>t</sup> (DSR2)			66 MHz			0.2		
<sup>t</sup> d(ZHLK)	High-impedance-state to-high delay (power up)		LOCK			3	ns	

NOTE 7: t<sub>(DSR1)</sub> represents the time required for the deserializer to register that a lock has occurred upon powerup or when leaving the powerdown mode. t<sub>(DSR2)</sub> represents the time required to register that a lock has occurred for the powered up and enabled deserializer when the input (RI±) conditions change from not receiving data to receiving synchronization patterns (SYNCPATs). In order to specify deserializer PLL performance t<sub>DSR1</sub> and t<sub>DSR2</sub> are specified with REFCLK active and stable and specific conditions of SYNCPATs.



## deserializer switching characteristics over recommended operating supply and temperature ranges (unless otherwise specified) (continued)

	PARAMETER	TEST CONDITIONS	PIN/FREQ	MIN	TYP	MAX	UNIT
<sup>t</sup> RNM	Deserializer noise	beschalizer holse occurrigate 17 and	30 MHz	1380			ps
	<sup>IM</sup> margin		66 MHz		540		

NOTE 8: tRNM represents the phase noise or jitter that the deserializer can withstand in the incoming data stream before bit errors occur.

#### timing diagrams and test circuits

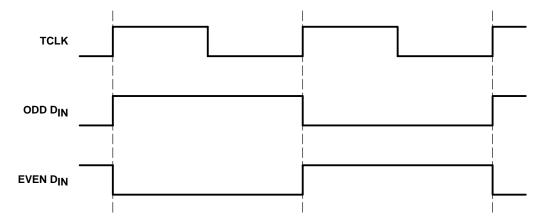


Figure 2. Worst-Case Serializer I<sub>CC</sub> Test Pattern

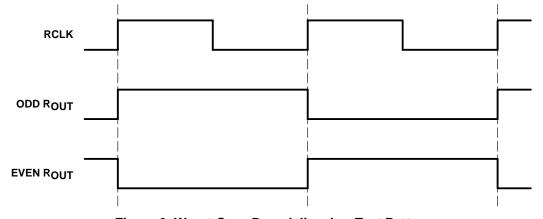


Figure 3. Worst-Case Deserializer I<sub>CC</sub> Test Pattern

## timing diagrams and test circuits (continued)

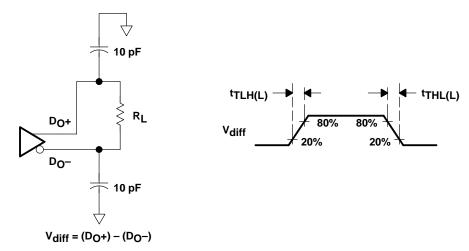


Figure 4. Serializer LVDS Output Load and Transition Times

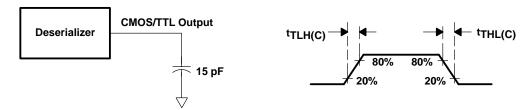


Figure 5. Deserializer CMOS/TTL Output Load and Transition Times

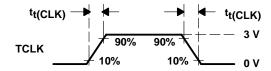


Figure 6. Serializer Input Clock Transition Time

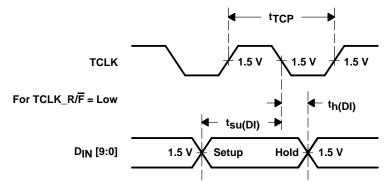


Figure 7. Serializer Setup/Hold Times

## timing diagrams and test circuits (continued)

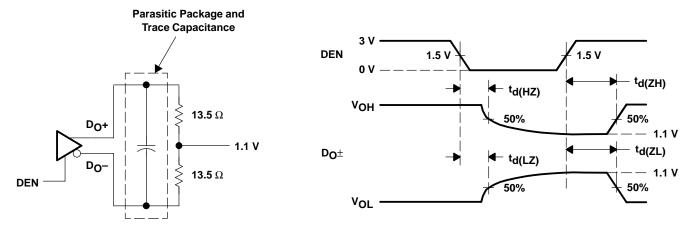


Figure 8. Serializer High-Impedance-State Test Circuit and Timing

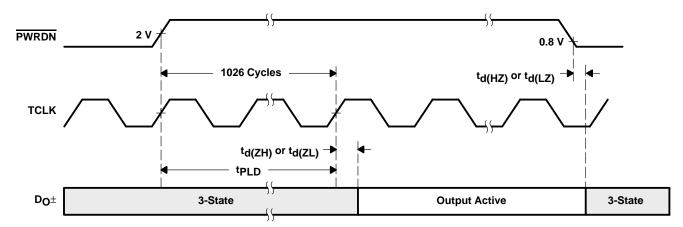
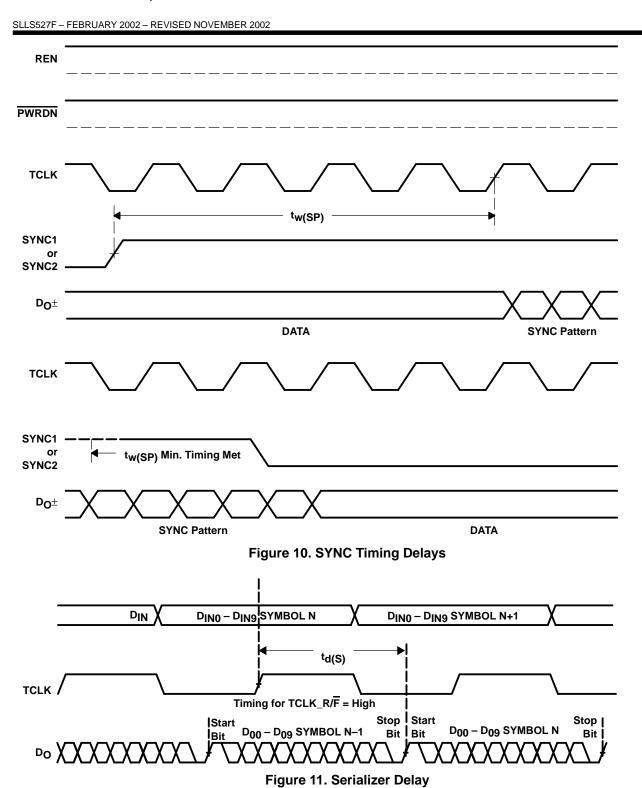


Figure 9. Serializer PLL Lock Time and PWRDN High-Impedance-State Delays





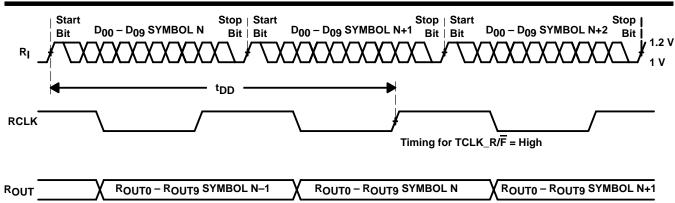


Figure 12. Deserializer Delay

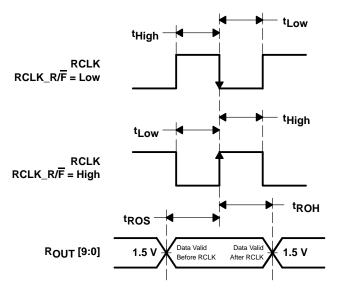


Figure 13. Deserializer Data Valid Out Times

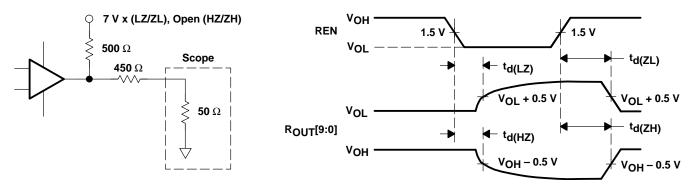


Figure 14. Deserializer High-Impedance-State Test Circuit and Timing

## timing diagrams and test circuits (continued)

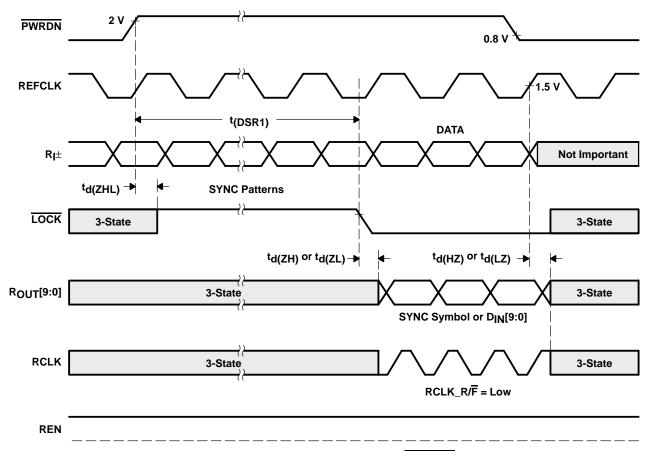


Figure 15. Deserializer PLL Lock Times and PWRDN 3-State Delays

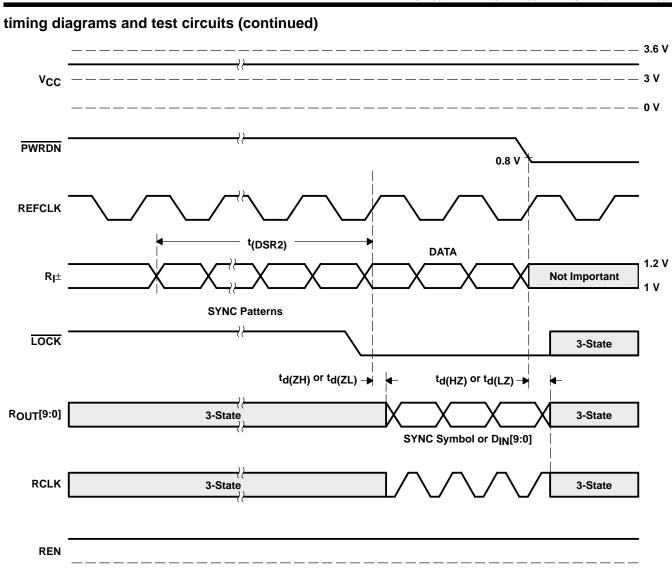
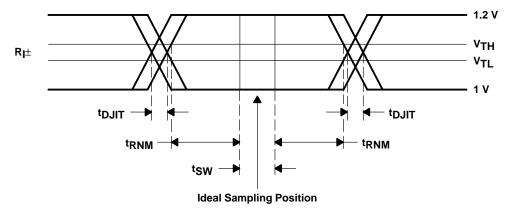


Figure 16. Deserilaizer PLL Lock Time From SyncPAT

## timing diagrams and test circuits (continued)

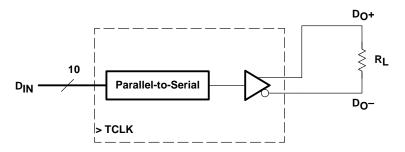


tSW: Setup and Hold Time (Internal Data Sampling Window)

tDJIT: Serializer Output Bit Position Jitter That Results From Jitter on TCLK

t<sub>RNM</sub>: Receiver Noise Margin Time

Figure 17. Receiver LVDS Input Skew Margin



 $V_{OD} = (D_O+) - (D_O-)$ Differential Output Signal Is Shown as  $(D_O+) - (D_O-)$ 

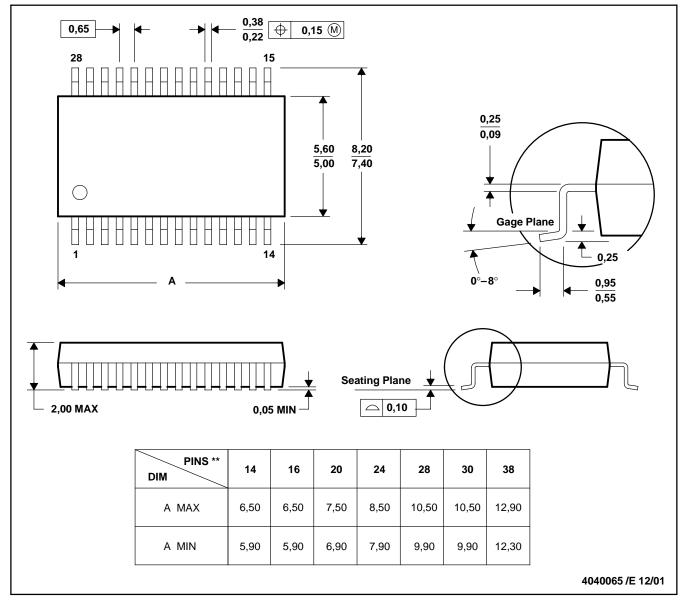
Figure 18. V<sub>OD</sub> Diagram

#### **MECHANICAL DATA**

## DB (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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